EPOXY RESIN COMPOSITION AND SEMICONDUCTOR DEVICE

ABSTRACT

There are provided an epoxy resin composition exhibiting less warpage after molding and during a solder treatment process as well as during a low temperature process of, for example, a temperature cycle test, and excellent in flame retardancy, solder crack resistance, and flowability; and a semiconductor device using the same. The epoxy resin composition used in the semiconductor device contains at least one type of epoxy resin (A) selected from a trifunctional epoxy resin and a tetrafunctional epoxy resin, a curing agent (B) having at least two hydroxyl groups per molecule, a compound (C) having at least two cyanate groups per molecule, and an inorganic filler (D), as essential components.

No Figure